



Material Content Data Sheet



Sales Product Name		ISO1H811G		Issued		20. July 2018		
MA#		MA001241508						
Package		PG-DSO-36-21		Weight*		2104.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	19.020	0.90	0.90	9036	9036
leadframe	inorganic material	phosphorus	7723-14-0	0.388	0.02		184	
	non noble metal	zinc	7440-66-6	1.553	0.07		738	
	non noble metal	iron	7439-89-6	31.066	1.48		14759	
wire	non noble metal	copper	7440-50-8	1261.410	59.95	61.52	599295	614976
	noble metal	gold	7440-57-5	4.075	0.19	0.19	1936	1936
	encapsulation	organic material	carbon black	1333-86-4	1.523	0.07		723
encapsulation	plastics	epoxy resin	-	70.041	3.33		33277	
	inorganic material	silicondioxide	60676-86-0	689.753	32.77	36.17	327701	361701
leadfinish	non noble metal	tin	7440-31-5	15.044	0.71	0.71	7147	7147
plating	noble metal	silver	7440-22-4	0.644	0.03	0.03	306	306
glue	plastics	Polyimide	26023-21-2	0.292	0.01	0.01	139	139
solder	noble metal	silver	7440-22-4	0.150	0.01		71	
	non noble metal	tin	7440-31-5	0.100	0.00		48	
	non noble metal	lead	7439-92-1	9.767	0.46	0.47	4640	4759
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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